ISEPT - China CALL FOR PAPERS

Sixth International Symposium on Aug. 30 - Sept. 2, 2005

Electronics Packaging Technology

Shenzhen, China

Who Should Attend: Attendees of this conference in the past have been researchers, developers, producers and users of packaging technology for IC, MEMS, optoelectronics, LEDs, LCDs, magnetic heads, sensors and PC Boards and assembly. There were over 400 attendees at the past five ISEPT conferences in China.

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Abstracts due May 25, 2005: If you are interested in presenting a paper at this conference, please send an abstract (500-1000 words) via email to wangcq@hit.edu.cn. Please include your affiliation, email address, postal code, mailing address, and phone number in your submission.

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